



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C470JB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47pF, 50V, ±5%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>470</u> <u>J</u> <u>B</u> <u>8</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor		
2	Size	0603 (inch code)	L: $1.6 \pm 0.1 \text{ mm}$	W: 0.8 ± 0.1 mm
3	Dielectric	C0G	Inner electrode	Ni
4	Capacitance	47 pF	Termination	Cu
⑤	Capacitance	±5 %	Plating	Sn 100% (Pb Free)
	tolerance		Product	Automotive
6	Rated Voltage	50 V	Grade code	Standard
7	Thickness	0.8 ± 0.1 mm	① Packaging	Cardboard Type, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150 ℃
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	
	Q: 1000 min	
	IR : More than 10,000№ or 500№×μF	
	Whichever is Smaller	
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles
	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :
	Q: 1000 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)
	IR : More than 10,000№ or 500№×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)
	Whichever is Smaller	
Destructive Physical	No Defects or abnormalities	Per EIA 469
Analysis		
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle
	Capacitance Change :	Heat (25~65°C) and humidity (80~98%), Unpowered
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion
	Q: 350 min	
	IR : More than 10,000№ or 500№×μF	
	Whichever is Smaller	
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,
	Capacitance Change :	Add 100kohm resistor
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion
	Q: 200 min	The charge/discharge current is less than 50mA.
	IR : More than 500MΩ or 25MΩ×μF	
	Whichever is Smaller	
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 ℃, 200% Rated Voltage,
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.
	Q: 350 min	
	IR : More than 10,000№ or 500№×μF	
	Whichever is Smaller	

	Performance	Test condition		
External Visual	No abnormal exterior appearance	Microscope ('10)		
Physical Dimensions	Within the specified dimensions	Using The calipers		
Mechanical Shock	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.		
Vibration	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000 Hz.		
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.		
Solder Heat	Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.			
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	-55 ℃/+125 ℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air		
ESD	Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec.	AEC-Q200-002		
Solderability	95% of the terminations is to be soldered evenly and continuously	 a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C solder: a solution ethanol and rosin 		
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,		
Characterization	Q: 1000 max. IR(25℃): More than 100,000 MΩ or 1,000 MΩ×μF IR(125℃): More than 10,000 MΩ or 100 MΩ×μF Whichever is Smaller Dielectric Strength	1Mb±10%, 0.5~5Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25℃, @125℃ for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds		
Board Flex	Appearance: No abnormal exterior appearance Capacitance Change: within ±5.0% or ±0.5pF whichever is larger	Bending to the limit (3mm) for 5 seconds		
Terminal	Appearance : No abnormal exterior appearance	10N, for 60±1 sec.		
Strength(SMD)	Capacitance Change : within ±2.5% or ±0.25pF whichever is larger			
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec		
Temperature	COG			
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/ ℃)			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.